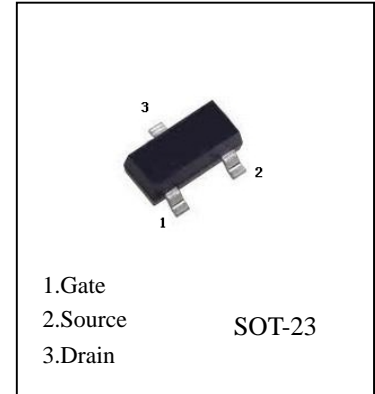
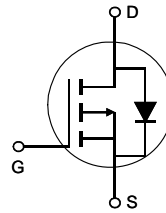


FEATURES

- The AO3403 uses advanced trench technology to provide excellent $R_{DS(ON)}$ and low gate charge. This device is suitable for use as a load switch or in PWM applications.

AO3403

P-Channel MOSFET



Absolute Maximum Ratings (TA=25°C, unless otherwise noted)

Parameter	Symbol	Maximum	Unit
Drain-Source Voltage	V_{DS}	-30	V
Gate-Source Voltage	V_{GS}	±12	V
Continuous Drain Current	I_D	$T_A=25^\circ\text{C}$	-2.6
		$T_A=70^\circ\text{C}$	-2.2
Pulsed Drain Current ^C	I_{DM}	-13	A
Power Dissipation ^B	P_D	$T_A=25^\circ\text{C}$	1.4
		$T_A=70^\circ\text{C}$	0.9
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 150	°C

Thermal Characteristics

Parameter	Symbol	Typ	Max	Unit
Maximum Junction-to-Ambient ^A	R_{JA}	70	90	°C/W
Maximum Junction-to-Ambient ^{A,D}				
Maximum Junction-to-Lead	R_{JL}	63	80	°C/W

AO3403

Electrical Characteristics (TA=25°C, unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	$I_D=-250\text{ A}, V_{GS}=0V$	-30			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=-30V, V_{GS}=0V$			-1	uA
		$T_J=55^\circ C$			-5	
I_{GSS}	Gate-Body leakage current	$V_{DS}=0V, V_{GS}=\pm 12V$			± 100	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=-250\text{ A}$	-0.6	-1	-1.4	V
$I_{D(ON)}$	On state drain current	$V_{GS}=-10V, V_{DS}=-5V$	-13			A
$R_{DS(on)}$	Static Drain-Source On-Resistance	$V_{GS}=-10V, I_D=-2.6A$		88	115	m
		$T_J=125^\circ C$		143	200	
		$V_{GS}=-4.5V, I_D=-2A$		103	150	m
		$V_{GS}=-2.5V, I_D=-1A$		139	200	m
g_{FS}	Forward Transconductance	$V_{DS}=-5V, I_D=-2.6A$		8		S
V_{SD}	Diode Forward Voltage	$I_S=-1A, V_{GS}=0V$		-0.78	-1	V
I_S	Maximum Body-Diode Continuous Current				-1.5	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	$V_{GS}=0V, V_{DS}=-15V, f=1MHz$		260	315	pF
C_{oss}	Output Capacitance		37		pF	
C_{rss}	Reverse Transfer Capacitance		20		pF	
R_g	Gate resistance	$V_{GS}=0V, V_{DS}=0V, f=1MHz$	4	8	12	
SWITCHING PARAMETERS						
$Q_g(10V)$	Total Gate Charge	$V_{GS}=-10V, V_{DS}=-15V, I_D=-2.6A$		5.9	7.2	nC
$Q_g(4.5V)$	Total Gate Charge		2.8	3.5		
Q_{gs}	Gate Source Charge		0.7			
Q_{gd}	Gate Drain Charge		1			
$t_{D(on)}$	Turn-On DelayTime	$V_{GS}=-10V, V_{DS}=-15V,$ $R_L=5.76, R_{GEN}=3$		6		ns
t_r	Turn-On Rise Time		3.5			
$t_{D(off)}$	Turn-Off DelayTime		20			
t_f	Turn-Off Fall Time		5			
t_{rr}	Body Diode Reverse Recovery Time	$I_F=-2.6A, dI/dt=100A/\mu s$		11.5	15	ns
Q_{rr}	Body Diode Reverse Recovery Charge	$I_F=-2.6A, dI/dt=100A/\mu s$		4.5		nC

A. The value of R_{JA} is measured with the device mounted on 1in2 FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ C$. The value in any given application depends on the user's specific board design.

B. The power dissipation P_D is based on $T_{J(MAX)}=150^\circ C$, using $\leq 10s$ junction-to-ambient thermal resistance.

C. Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}=150^\circ C$. Ratings are based on low frequency and duty cycles to keep initial $T_J=25^\circ C$.

D. The R_{JA} is the sum of the thermal impedance from junction to lead R_{JL} and lead to ambient.

E. The static characteristics in Figures 1 to 6 are obtained using $<300\mu s$ pulses, duty cycle 0.5% max.

F. These curves are based on the junction-to-ambient thermal impedance which is measured with the device mounted on 1in2 FR-4 board with 2oz. Copper, assuming a maximum junction temperature of $T_{J(MAX)}=150^\circ C$. The SOA curve provides a single pulse rating.

AO3403 Typical Characteristics

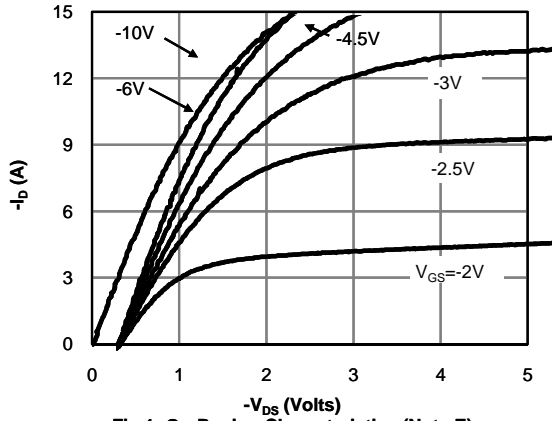


Fig 1: On-Region Characteristics (Note E)

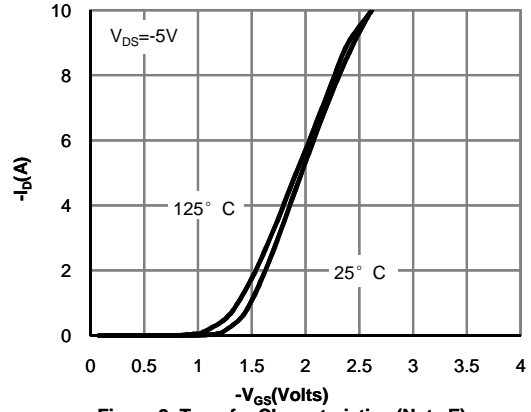


Figure 2: Transfer Characteristics (Note E)

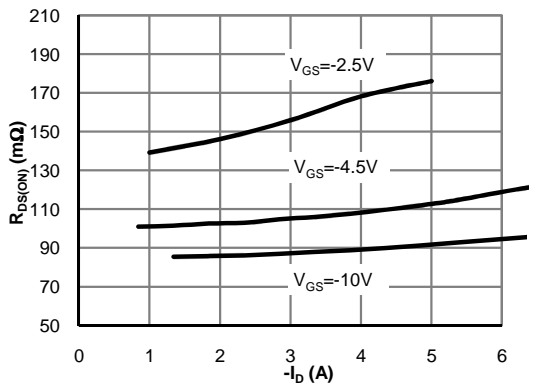


Figure 3: On-Resistance vs. Drain Current and Gate Voltage (Note E)

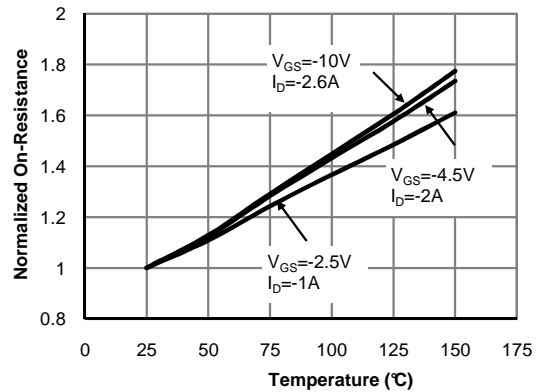


Figure 4: On-Resistance vs. Junction Temperature (Note E)

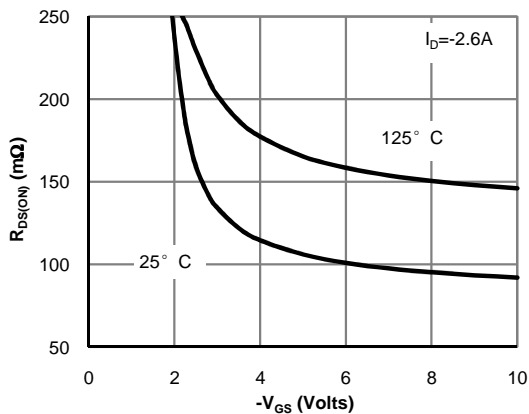


Figure 5: On-Resistance vs. Gate-Source Voltage (Note E)

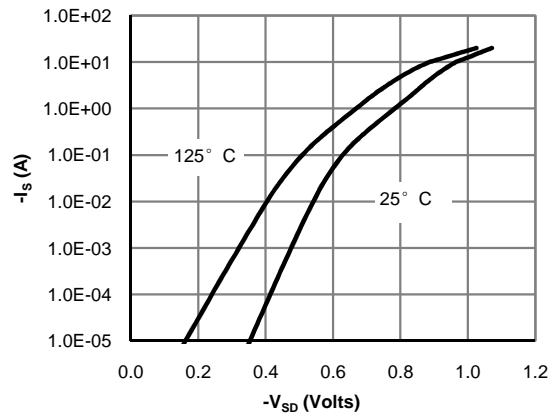


Figure 6: Body-Diode Characteristics (Note E)

AO3403 Typical Characteristics

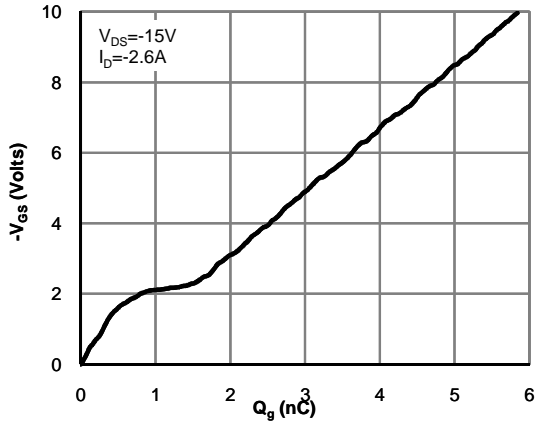


Figure 7: Gate-Charge Characteristics

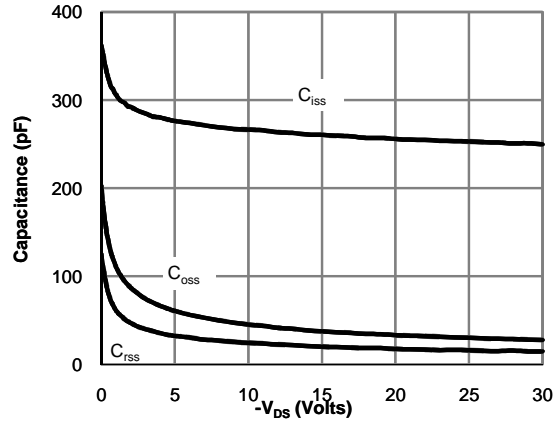


Figure 8: Capacitance Characteristics

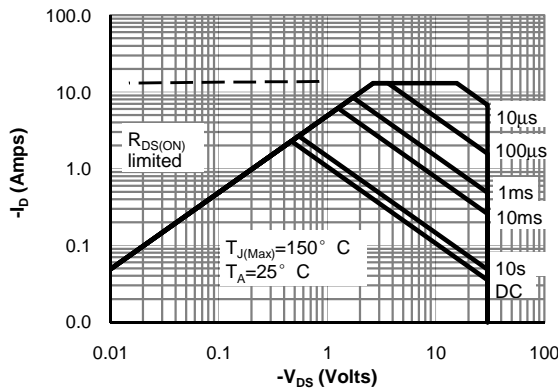


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

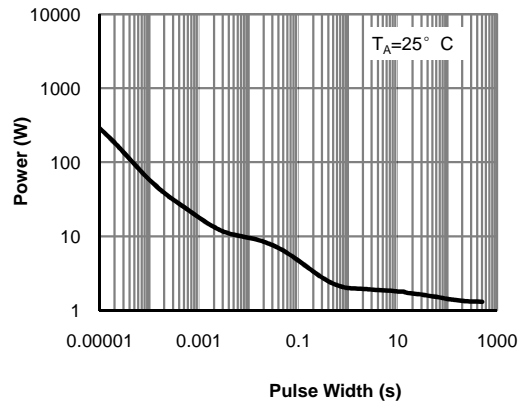


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note F)

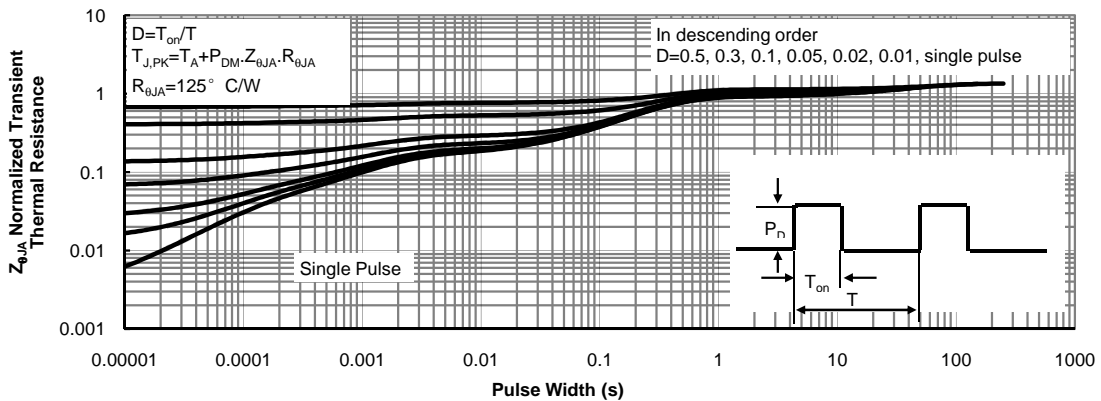


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)